

Electronic Patent Application Fee Transmittal

Application Number:	10529742			
Filing Date:	06-Jan-2006			
Title of Invention:	POLISHING PAD FOR SEMICONDUCTOR WAFER, POLISHING MULTILAYERED BODY FOR SEMICONDUCTOR WAFER HAVING SAME, AND METHOD FOR POLISHING SEMICONDUCTOR WAFER			
First Named Inventor/Applicant Name:	Hiroshi Shiho			
Filer:	Marvin Jay Spivak/Slobodanka Alic			
Attorney Docket Number:	268844USOPCT			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	3	3	9
Total in USD (\$)				1749